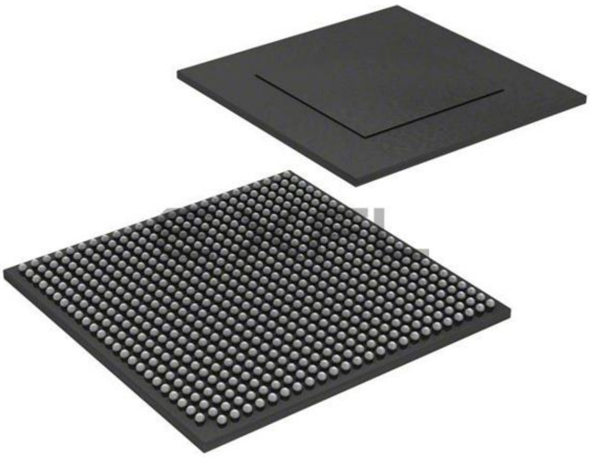

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	ARM® Cortex®-A9
Number of Cores/Bus Width	2 Core, 32-Bit
Speed	1.0GHz
Co-Processors/DSP	Multimedia; NEON™ SIMD
RAM Controllers	LPDDR2, LVDDR3, DDR3
Graphics Acceleration	Yes
Display & Interface Controllers	Keypad, LCD
Ethernet	10/100/1000Mbps (1)
SATA	SATA 3Gbps (1)
USB	USB 2.0 + PHY (4)
Voltage - I/O	1.8V, 2.5V, 2.8V, 3.3V
Operating Temperature	-40°C ~ 125°C (TJ)
Security Features	ARM TZ, Boot Security, Cryptography, RTIC, Secure Fusebox, Secure JTAG, Secure Memory, Secure RTC, Tamper Detection
Package / Case	624-FBGA, FCBGA
Supplier Device Package	624-FCBGA (21x21)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mcimx6d6avt10ad

- Displays—Total five interfaces available. Total raw pixel rate of all interfaces is up to 450 Mpixels/sec, 24 bpp. Up to four interfaces may be active in parallel.
  - One Parallel 24-bit display port, up to 225 Mpixels/sec (for example, WUXGA at 60 Hz or dual HD1080 and WXGA at 60 Hz)
  - LVDS serial ports—One port up to 165 Mpixels/sec or two ports up to 85 MP/sec (for example, WUXGA at 60 Hz) each
  - HDMI 1.4 port
  - MIPI/DSI, two lanes at 1 Gbps
- Camera sensors:
  - Parallel Camera port (up to 20 bit and up to 240 MHz peak)
  - MIPI CSI-2 serial camera port, supporting up to 1000 Mbps/lane in 1/2/3-lane mode and up to 800 Mbps/lane in 4-lane mode. The CSI-2 Receiver core can manage one clock lane and up to four data lanes. Each i.MX 6Dual/6Quad processor has four lanes.
- Expansion cards:
  - Four MMC/SD/SDIO card ports all supporting:
    - 1-bit or 4-bit transfer mode specifications for SD and SDIO cards up to UHS-I SDR-104 mode (104 MB/s max)
    - 1-bit, 4-bit, or 8-bit transfer mode specifications for MMC cards up to 52 MHz in both SDR and DDR modes (104 MB/s max)
- USB:
  - One High Speed (HS) USB 2.0 OTG (Up to 480 Mbps), with integrated HS USB PHY
  - Three USB 2.0 (480 Mbps) hosts:
    - One HS host with integrated High Speed PHY
    - Two HS hosts with integrated HS-IC USB (High Speed Inter-Chip USB) PHY
- Expansion PCI Express port (PCIe) v2.0 one lane
  - PCI Express (Gen 2.0) dual mode complex, supporting Root complex operations and Endpoint operations. Uses x1 PHY configuration.
- Miscellaneous IPs and interfaces:
  - SSI block capable of supporting audio sample frequencies up to 192 kHz stereo inputs and outputs with I^2S mode
  - ESAI is capable of supporting audio sample frequencies up to 260kHz in I2S mode with 7.1 multi channel outputs
  - Five UARTs, up to 5.0 Mbps each:
    - Providing RS232 interface
    - Supporting 9-bit RS485 multidrop mode
    - One of the five UARTs (UART1) supports 8-wire while others four supports 4-wire. This is due to the SoC IOMUX limitation, since all UART IPs are identical.
  - Five eCSPI (Enhanced CSPI)
  - Three I2C, supporting 400 kbps

— Gigabit Ethernet Controller (IEEE1588 compliant), 10/100/1000[1] Mbps
— Four Pulse Width Modulators (PWM)
— System JTAG Controller (SJC)
— GPIO with interrupt capabilities
— 8x8 Key Pad Port (KPP)
— Sony Philips Digital Interconnect Format (SPDIF), Rx and Tx
— Two Controller Area Network (FlexCAN), 1 Mbps each
— Two Watchdog timers (WDOG)
— Audio MUX (AUDMUX)
— MLB (MediaLB) provides interface to MOST Networks (150 Mbps) with the option of DTCP cipher accelerator

The i.MX 6Dual/6Quad processors integrate advanced power management unit and controllers:

- Provide PMU, including LDO supplies, for on-chip resources
- Use Temperature Sensor for monitoring the die temperature
- Support DVFS techniques for low power modes
- Use Software State Retention and Power Gating for ARM and MPE
- Support various levels of system power modes
- Use flexible clock gating control scheme

The i.MX 6Dual/6Quad processors use dedicated hardware accelerators to meet the targeted multimedia performance. The use of hardware accelerators is a key factor in obtaining high performance at low power consumption numbers, while having the CPU core relatively free for performing other tasks.

The i.MX 6Dual/6Quad processors incorporate the following hardware accelerators:

- VPU—Video Processing Unit
- IPUv3H—Image Processing Unit version 3H (2 IPUs)
- GPU3Dv4—3D Graphics Processing Unit (OpenGL ES 2.0) version 4
- GPU2Dv2—2D Graphics Processing Unit (BitBlt)
- GPUVG—OpenVG 1.1 Graphics Processing Unit
- ASRC—Asynchronous Sample Rate Converter

Security functions are enabled and accelerated by the following hardware:

- ARM TrustZone including the TZ architecture (separation of interrupts, memory mapping, etc.)
- SJC—System JTAG Controller. Protecting JTAG from debug port attacks by regulating or blocking the access to the system debug features.
- CAAM—Cryptographic Acceleration and Assurance Module, containing 16 KB secure RAM and True and Pseudo Random Number Generator (NIST certified)
- SNVS—Secure Non-Volatile Storage, including Secure Real Time Clock

1. The theoretical maximum performance of 1 Gbps ENET is limited to 470 Mbps (total for Tx and Rx) due to internal bus throughput limitations. The actual measured performance in optimized environment is up to 400 Mbps. For details, see the ERR004512 erratum in the i.MX 6Dual/6Quad errata document (IMX6DQCE).

3 Modules List

The i.MX 6Dual/6Quad processors contain a variety of digital and analog modules. Table 2 describes these modules in alphabetical order.

Table 2. i.MX 6Dual/6Quad Modules List

Block Mnemonic	Block Name	Subsystem	Brief Description
512x8 Fuse Box	Electrical Fuse Array	Security	Electrical Fuse Array. Enables to setup Boot Modes, Security Levels, Security Keys, and many other system parameters. The i.MX 6Dual/6Quad processors consist of 512x8-bit fuse box accessible through OCOTP_CTRL interface.
APBH-DMA	NAND Flash and BCH ECC DMA Controller	System Control Peripherals	DMA controller used for GPMI2 operation
ARM	ARM Platform	ARM	The ARM Cortex-A9 platform consists of 4x (four) Cortex-A9 cores version r2p10 and associated sub-blocks, including Level 2 Cache Controller, SCU (Snoop Control Unit), GIC (General Interrupt Controller), private timers, Watchdog, and CoreSight debug modules.
ASRC	Asynchronous Sample Rate Converter	Multimedia Peripherals	The Asynchronous Sample Rate Converter (ASRC) converts the sampling rate of a signal associated to an input clock into a signal associated to a different output clock. The ASRC supports concurrent sample rate conversion of up to 10 channels of about -120dB THD+N. The sample rate conversion of each channel is associated to a pair of incoming and outgoing sampling rates. The ASRC supports up to three sampling rate pairs.
AUDMUX	Digital Audio Mux	Multimedia Peripherals	The AUDMUX is a programmable interconnect for voice, audio, and synchronous data routing between host serial interfaces (for example, SSI1, SSI2, and SSI3) and peripheral serial interfaces (audio and voice codecs). The AUDMUX has seven ports with identical functionality and programming models. A desired connectivity is achieved by configuring two or more AUDMUX ports.
BCH40	Binary-BCH ECC Processor	System Control Peripherals	The BCH40 module provides up to 40-bit ECC encryption/decryption for NAND Flash controller (GPMI)
CAAM	Cryptographic Accelerator and Assurance Module	Security	CAAM is a cryptographic accelerator and assurance module. CAAM implements several encryption and hashing functions, a run-time integrity checker, and a Pseudo Random Number Generator (PRNG). The pseudo random number generator is certified by Cryptographic Algorithm Validation Program (CAVP) of National Institute of Standards and Technology (NIST). Its DRBG validation number is 94 and its SHS validation number is 1455. CAAM also implements a Secure Memory mechanism. In i.MX 6Dual/6Quad processors, the security memory provided is 16 KB.
CCM GPC SRC	Clock Control Module, General Power Controller, System Reset Controller	Clocks, Resets, and Power Control	These modules are responsible for clock and reset distribution in the system, and also for the system power management.

Table 2. i.MX 6Dual/6Quad Modules List (continued)

Block Mnemonic	Block Name	Subsystem	Brief Description
CSI	MIPI CSI-2 Interface	Multimedia Peripherals	The CSI IP provides MIPI CSI-2 standard camera interface port. The CSI-2 interface supports up to 1 Gbps for up to 3 data lanes and up to 800 Mbps for 4 data lanes.
CSU	Central Security Unit	Security	The Central Security Unit (CSU) is responsible for setting comprehensive security policy within the i.MX 6Dual/6Quad platform. The Security Control Registers (SCR) of the CSU are set during boot time by the HAB and are locked to prevent further writing.
CTI-0 CTI-1 CTI-2 CTI-3 CTI-4	Cross Trigger Interfaces	Debug / Trace	Cross Trigger Interfaces allows cross-triggering based on inputs from masters attached to CTIs. The CTI module is internal to the Cortex-A9 Core Platform.
CTM	Cross Trigger Matrix	Debug / Trace	Cross Trigger Matrix IP is used to route triggering events between CTIs. The CTM module is internal to the Cortex-A9 Core Platform.
DAP	Debug Access Port	System Control Peripherals	The DAP provides real-time access for the debugger without halting the core to: • System memory and peripheral registers • All debug configuration registers The DAP also provides debugger access to JTAG scan chains. The DAP module is internal to the Cortex-A9 Core Platform.
DCIC-0 DCIC-1	Display Content Integrity Checker	Automotive IP	The DCIC provides integrity check on portion(s) of the display. Each i.MX 6Dual/6Quad processor has two such modules, one for each IPU.
DSI	MIPI DSI interface	Multimedia Peripherals	The MIPI DSI IP provides DSI standard display port interface. The DSI interface support 80 Mbps to 1 Gbps speed per data lane.
DTCP	DTCP	MM	Provides encryption function according to Digital Transmission Content Protection standard for traffic over MLB150.
eCSPI1-5	Configurable SPI	Connectivity Peripherals	Full-duplex enhanced Synchronous Serial Interface. It is configurable to support Master/Slave modes, four chip selects to support multiple peripherals.
ENET	Ethernet Controller	Connectivity Peripherals	The Ethernet Media Access Controller (MAC) is designed to support 10/100/1000 Mbps Ethernet/IEEE 802.3 networks. An external transceiver interface and transceiver function are required to complete the interface to the media. The i.MX 6Dual/6Quad processors also consist of hardware assist for IEEE 1588 standard. For details, see the ENET chapter of the i.MX 6Dual/6Quad reference manual (IMX6DQRM). **Note:** The theoretical maximum performance of 1 Gbps ENET is limited to 470 Mbps (total for Tx and Rx) due to internal bus throughput limitations. The actual measured performance in optimized environment is up to 400 Mbps. For details, see the ERR004512 erratum in the i.MX 6Dual/6Quad errata document (IMX6DQCE).

Table 2. i.MX 6Dual/6Quad Modules List (continued)

Block Mnemonic	Block Name	Subsystem	Brief Description
GPU2Dv2	Graphics Processing Unit-2D, ver. 2	Multimedia Peripherals	The GPU2Dv2 provides hardware acceleration for 2D graphics algorithms, such as Bit BLT, stretch BLT, and many other 2D functions.
GPU2Dv4	Graphics Processing Unit, ver. 4	Multimedia Peripherals	The GPU2Dv4 provides hardware acceleration for 3D graphics algorithms with sufficient processor power to run desktop quality interactive graphics applications on displays up to HD1080 resolution. The GPU3D provides OpenGL ES 2.0, including extensions, OpenGL ES 1.1, and OpenVG 1.1
GPUVGv2	Vector Graphics Processing Unit, ver. 2	Multimedia Peripherals	OpenVG graphics accelerator provides OpenVG 1.1 support as well as other accelerations, including Real-time hardware curve tesselation of lines, quadratic and cubic Bezier curves, 16x Line Anti-aliasing, and various Vector Drawing functions.
HDMI Tx	HDMI Tx interface	Multimedia Peripherals	The HDMI module provides HDMI standard interface port to an HDMI 1.4 compliant display.
HSI	MIPI HSI interface	Connectivity Peripherals	The MIPI HSI provides a standard MIPI interface to the applications processor.
I^2C-1 I^2C-2 I^2C-3	I^2C Interface	Connectivity Peripherals	I^2C provide serial interface for external devices. Data rates of up to 400 kbps are supported.
IOMUXC	IOMUX Control	System Control Peripherals	This module enables flexible IO multiplexing. Each IO pad has default and several alternate functions. The alternate functions are software configurable.
IPUv3H-1 IPUv3H-2	Image Processing Unit, ver. 3H	Multimedia Peripherals	IPUv3H enables connectivity to displays and video sources, relevant processing and synchronization and control capabilities, allowing autonomous operation. The IPUv3H supports concurrent output to two display ports and concurrent input from two camera ports, through the following interfaces: • Parallel Interfaces for both display and camera • Single/dual channel LVDS display interface • HDMI transmitter • MIPI/DSI transmitter • MIPI/CSI-2 receiver The processing includes: • Image conversions: resizing, rotation, inversion, and color space conversion • A high-quality de-interlacing filter • Video/graphics combining • Image enhancement: color adjustment and gamut mapping, gamma correction, and contrast enhancement • Support for display backlight reduction
KPP	Key Pad Port	Connectivity Peripherals	KPP Supports 8 x 8 external key pad matrix. KPP features are: • Open drain design • Glitch suppression circuit design • Multiple keys detection • Standby key press detection

4.1.3 Operating Ranges

Table 6 provides the operating ranges of the i.MX 6Dual/6Quad processors.

Table 6. Operating Ranges

Parameter Description	Symbol	Min	Typ	Max[1]	Unit	Comment[2]
Run mode: LDO enabled	VDD_ARM_IN VDD_ARM23_IN[3]	1.35[4]	—	1.5	V	LDO Output Set Point (VDD_ARM_CAP[5]) of 1.225 V minimum for operation up to 852 MHz or 996 MHz (depending on the device speed grade).
		1.275[4]	—	1.5	V	LDO Output Set Point (VDD_ARM_CAP[5]) of 1.150 V minimum for operation up to 792 MHz.
		1.05[4]	—	1.5	V	LDO Output Set Point (VDD_ARM_CAP[5]) of 0.925 V minimum for operation up to 396 MHz.
	VDD_SOC_IN[6]	1.350[4]	—	1.5	V	264 MHz < VPU ≤ 352 MHz; VDDSOC and VDDPU LDO outputs (VDD_SOC_CAP and VDD_PU_CAP) require 1.225 V minimum.
		1.275[4,7]	—	1.5	V	VPU ≤ 264 MHz; VDDSOC and VDDPU LDO outputs (VDD_SOC_CAP and VDD_PU_CAP) require 1.15 V minimum.
Run mode: LDO bypassed[8]	VDD_ARM_IN VDD_ARM23_IN[3]	1.225	—	1.3	V	LDO bypassed for operation up to 852 MHz or 996 MHz (depending on the device speed grade).
		1.150	—	1.3	V	LDO bypassed for operation up to 792 MHz.
		0.925	—	1.3	V	LDO bypassed for operation up to 396 MHz.
	VDD_SOC_IN[6]	1.225	—	1.3	V	264 MHz < VPU ≤ 352 MHz
		1.15	—	1.3	V	VPU ≤ 264 MHz
Standby/DSM mode	VDD_ARM_IN VDD_ARM23_IN[3]	0.9	—	1.3	V	See Table 9, "Stop Mode Current and Power Consumption," on page 26.
	VDD_SOC_IN	0.9	—	1.3	V	
VDD_HIGH internal regulator	VDD_HIGH_IN[9]	2.7	—	3.3	V	Must match the range of voltages that the rechargeable backup battery supports.
Backup battery supply range	VDD_SNVS_IN[9]	2.8	—	3.3	V	Should be supplied from the same supply as VDD_HIGH_IN, if the system does not require keeping real time and other data on OFF state.
USB supply voltages	USB_OTG_VBUS	4.4	—	5.25	V	—
	USB_H1_VBUS	4.4	—	5.25	V	—
DDR I/O supply	NVCC_DRAM	1.14	1.2	1.3	V	LPDDR2
		1.425	1.5	1.575	V	DDR3
		1.283	1.35	1.45	V	DDR3_L
Supply for RGMII I/O power group[10]	NVCC_RGMII	1.15	—	2.625	V	• 1.15 V – 1.30 V in HSIC 1.2 V mode • 1.43 V – 1.58 V in RGMII 1.5 V mode • 1.70 V – 1.90 V in RGMII 1.8 V mode • 2.25 V – 2.625 V in RGMII 2.5 V mode

Table 6. Operating Ranges (continued)

Parameter Description	Symbol	Min	Typ	Max[1]	Unit	Comment[2]
GPIO supplies[10]	NVCC_CSI, NVCC_EIM0, NVCC_EIM1, NVCC_EIM2, NVCC_ENET, NVCC_GPIO, NVCC_LCD, NVCC_NANDF, NVCC_SD1, NVCC_SD2, NVCC_SD3, NVCC_JTAG	1.65	1.8, 2.8, 3.3	3.6	V	Isolation between the NVCC_EIMx and NVCC_SDx different supplies allow them to operate at different voltages within the specified range. Example: NVCC_EIM1 can operate at 1.8 V while NVCC_EIM2 operates at 3.3 V.
	NVCC_LVDS_2P5[11] NVCC_MIPI	2.25	2.5	2.75	V	—
HDMI supply voltages	HDMI_VP	0.99	1.1	1.3	V	—
	HDMI_VPH	2.25	2.5	2.75	V	—
PCIe supply voltages	PCIE_VP	1.023	1.1	1.3	V	—
	PCIE_VPH	2.325	2.5	2.75	V	—
	PCIE_VPTX	1.023	1.1	1.3	V	—
SATA Supply voltages	SATA_VP	0.99	1.1	1.3	V	—
	SATA_VPH	2.25	2.5	2.75	V	—
Junction temperature	T_J	-40	95	125	°C	See *i.MX 6Dual/6Quad Product Lifetime Usage Estimates Application Note*, AN4724, for information on product lifetime (power-on years) for this processor.

1 Applying the maximum voltage results in maximum power consumption and heat generation. Freescale recommends a voltage set point = (Vmin + the supply tolerance). This results in an optimized power/speed ratio.

2 See the *Hardware Development Guide for i.MX 6Quad, 6Dual, 6DualLite, 6Solo Families of Applications Processors* (IMX6DQ6SDLHDG) for bypass capacitors requirements for each of the *_CAP supply outputs.

3 For Quad core system, connect to VDD_ARM_IN. For Dual core system, may be shorted to GND together with VDD_ARM23_CAP to reduce leakage.

4 VDD_ARM_IN and VDD_SOC_IN must be at least 125 mV higher than the LDO Output Set Point for correct voltage regulation.

5 VDD_ARM_CAP must not exceed VDD_CACHE_CAP by more than +50 mV. VDD_CACHE_CAP must not exceed VDD_ARM_CAP by more than 200 mV.

6 VDD_SOC_CAP and VDD_PU_CAP must be equal.

7 In LDO enabled mode, the internal LDO output set points must be configured such that the:

VDD_ARM LDO output set point does not exceed the VDD_SOC LDO output set point by more than 100 mV.

VDD_SOC LDO output set point is equal to the VDD_PU LDO output set point.

The VDD_ARM LDO output set point can be lower than the VDD_SOC LDO output set point, however, the minimum output set points shown in this table must be maintained.

8 In LDO bypassed mode, the external power supply must ensure that VDD_ARM_IN does not exceed VDD_SOC_IN by more than 100 mV. The VDD_ARM_IN supply voltage can be lower than the VDD_SOC_IN supply voltage. The minimum voltages shown in this table must be maintained.

9 To set VDD_SNVS_IN voltage with respect to Charging Currents and RTC, see the *Hardware Development Guide for i.MX 6Dual, 6Quad, 6Solo, 6DualLite Families of Applications Processors* (IMX6DQ6SDLHDG).

Table 26. MLB I/O DC Parameters

Parameter	Symbol	Test Conditions	Min	Max	Unit
Output Differential Voltage	V_{OD}	Rload = 50 Ω between padP and padN	300	500	mV
Output High Voltage	V_{OH}		1.15	1.75	V
Output Low Voltage	V_{OL}		0.75	1.35	V
Common-mode Output Voltage ((Vpad_P + Vpad_N) / 2))	V_{OCM}		1	1.5	V
Differential Output Impedance	Z_O	—	1.6	—	kΩ

4.7 I/O AC Parameters

This section includes the AC parameters of the following I/O types:

- General Purpose I/O (GPIO)
- Double Data Rate I/O (DDR) for LPDDR2 and DDR3/DDR3L modes
- LVDS I/O
- MLB I/O

The GPIO and DDR I/O load circuit and output transition time waveforms are shown in Figure 4 and Figure 5.

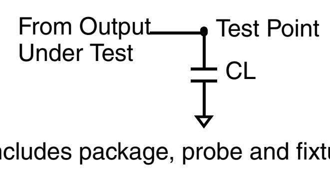


Figure 4. Load Circuit for Output

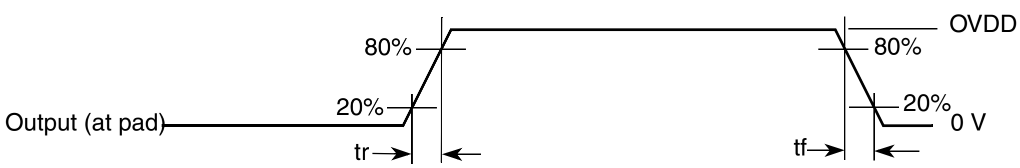


Figure 5. Output Transition Time Waveform

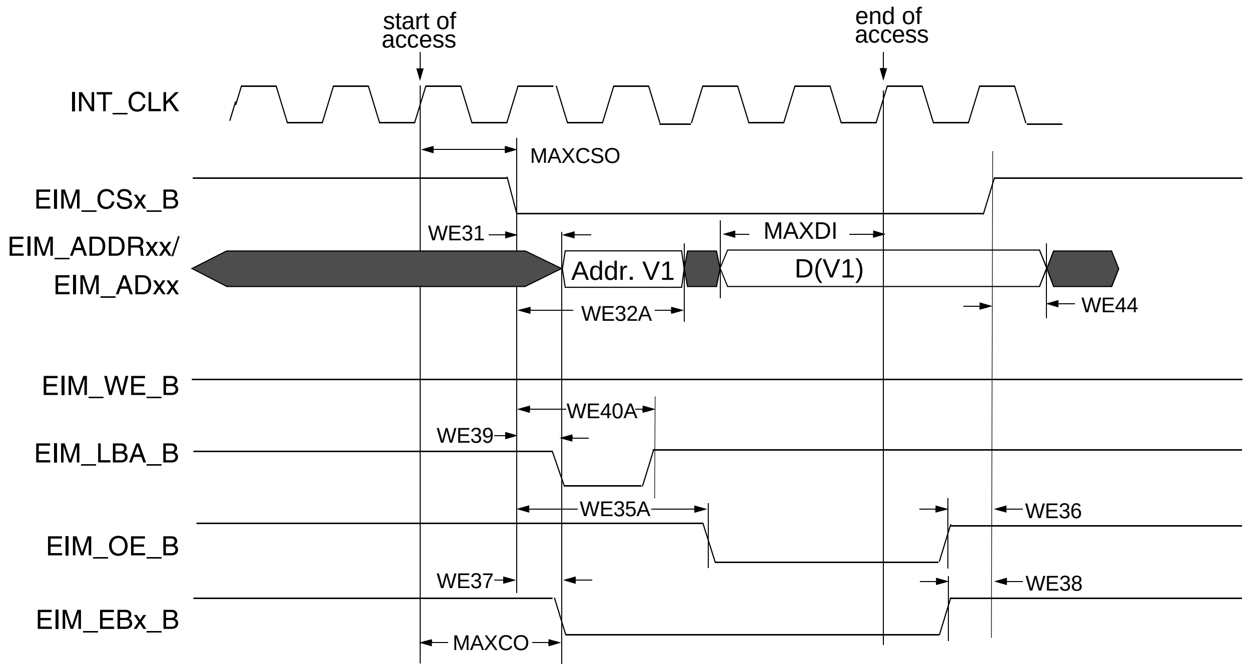


Figure 19. Asynchronous A/D Muxed Read Access (RWSC = 5)

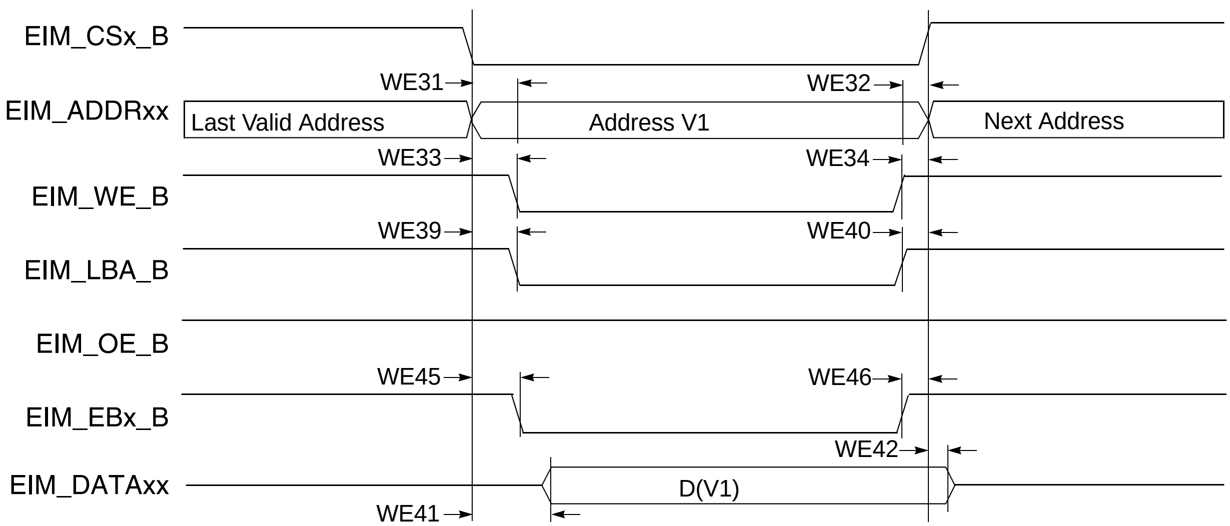


Figure 20. Asynchronous Memory Write Access

4.10.1 Asynchronous Mode AC Timing (ONFI 1.0 Compatible)

Asynchronous mode AC timings are provided as multiplications of the clock cycle and fixed delay. The Maximum I/O speed of GPMI in Asynchronous mode is about 50 MB/s. Figure 30 through Figure 33 depict the relative timing between GPMI signals at the module level for different operations under Asynchronous mode. Table 48 describes the timing parameters (NF1–NF17) that are shown in the figures.

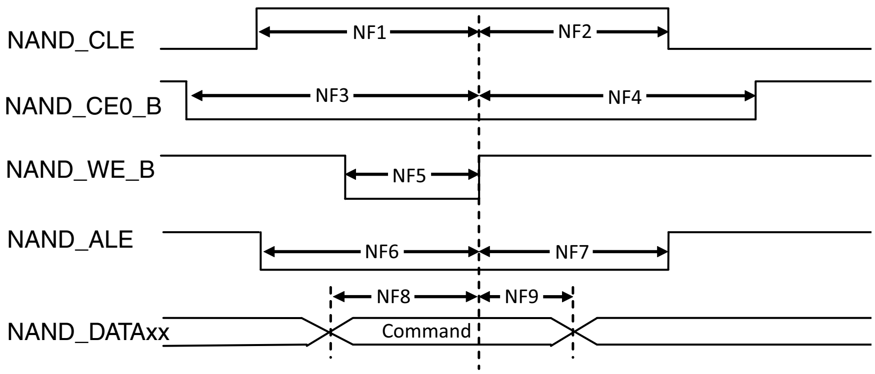


Figure 30. Command Latch Cycle Timing Diagram

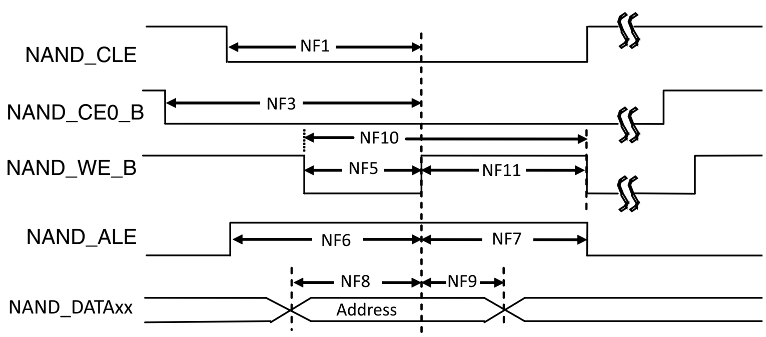


Figure 31. Address Latch Cycle Timing Diagram

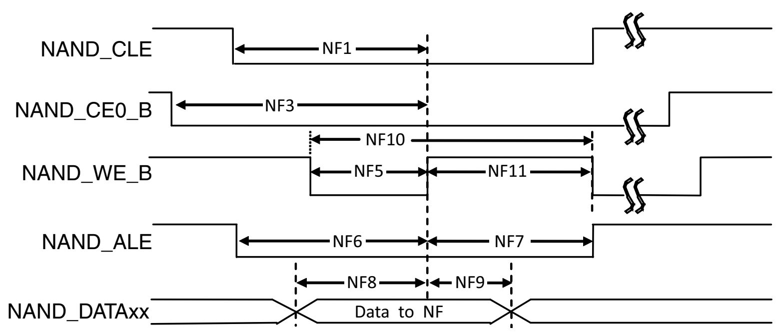


Figure 32. Write Data Latch Cycle Timing Diagram

4.11.5.1.2 MII Transmit Signal Timing (ENET_TX_DATA3,2,1,0, ENET_TX_EN, ENET_TX_ER, and ENET_TX_CLK)

The transmitter functions correctly up to an ENET_TX_CLK maximum frequency of 25 MHz + 1%. There is no minimum frequency requirement. Additionally, the processor clock frequency must exceed twice the ENET_TX_CLK frequency.

Figure 49 shows MII transmit signal timings. Table 58 describes the timing parameters (M5–M8) shown in the figure.

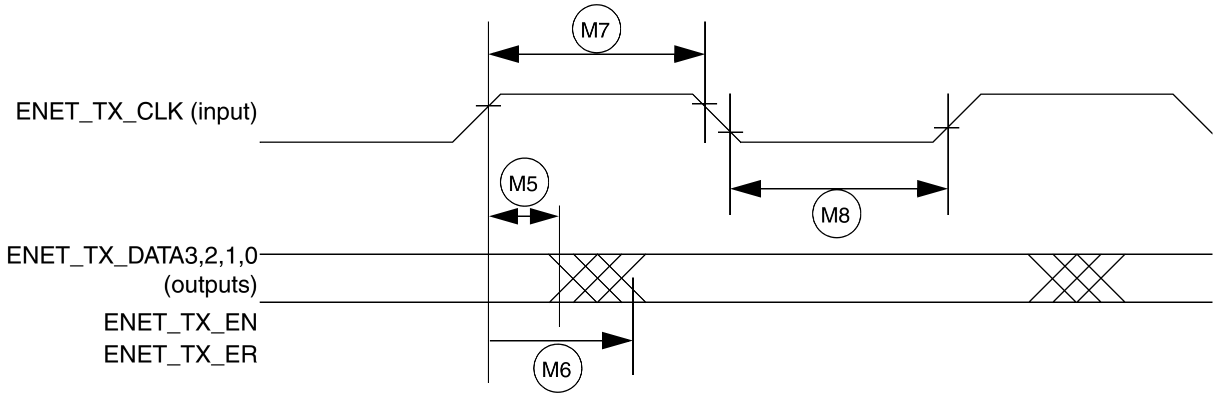


Figure 49. MII Transmit Signal Timing Diagram

Table 58. MII Transmit Signal Timing

ID	Characteristic[1]	Min	Max	Unit
M5	ENET_TX_CLK to ENET_TX_DATA3,2,1,0, ENET_TX_EN, ENET_TX_ER invalid	5	—	ns
M6	ENET_TX_CLK to ENET_TX_DATA3,2,1,0, ENET_TX_EN, ENET_TX_ER valid	—	20	ns
M7	ENET_TX_CLK pulse width high	35%	65%	ENET_TX_CLK period
M8	ENET_TX_CLK pulse width low	35%	65%	ENET_TX_CLK period

[1] ENET_TX_EN, ENET_TX_CLK, and ENET0_TXD0 have the same timing in 10-Mbps 7-wire interface mode.

4.11.5.1.3 MII Asynchronous Inputs Signal Timing (ENET_CRS and ENET_COL)

Figure 50 shows MII asynchronous input timings. Table 59 describes the timing parameter (M9) shown in the figure.

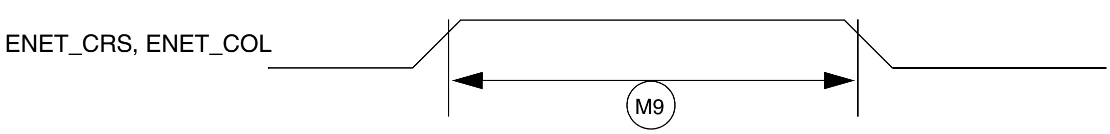


Figure 50. MII Async Inputs Timing Diagram

Table 68. Video Signal Cross-Reference (continued)

i.MX 6Dual/6Quad	LCD							Comment[1,2]
Port Name (x = 0, 1)	RGB, Signal Name (General)	RGB/TV Signal Allocation (Example)						
		16-bit RGB	18-bit RGB	24 Bit RGB	8-bit YCrCb[3]	16-bit YCrCb	20-bit YCrCb	
IPUx_DIx_D0_CS	—							—
IPUx_DIx_D1_CS	—							Alternate mode of PWM output for contrast or brightness control
IPUx_DIx_PIN11	—							—
IPUx_DIx_PIN12	—							—
IPUx_DIx_PIN13	—							Register select signal
IPUx_DIx_PIN14	—							Optional RS2
IPUx_DIx_PIN15	DRDY/DV							Data validation/blank, data enable
IPUx_DIx_PIN16	—							Additional data synchronous signals with programmable features/timing
IPUx_DIx_PIN17	Q							

1 Signal mapping (both data and control/synchronization) is flexible. The table provides examples.

2 Restrictions for ports IPUx_DISPx_DAT00 through IPUx_DISPx_DAT23 are as follows:
- A maximum of three continuous groups of bits can be independently mapped to the external bus. Groups must not overlap.
- The bit order is expressed in each of the bit groups, for example, B[0] = least significant blue pixel bit.

3 This mode works in compliance with recommendation ITU-R BT.656. The timing reference signals (frame start, frame end, line start, and line end) are embedded in the 8-bit data bus. Only video data is supported, transmission of non-video related data during blanking intervals is not supported.

NOTE

Table 68 provides information for both the DISP0 and DISP1 ports. However, DISP1 port has reduced pinout depending on IOMUXC configuration and therefore may not support all configurations. See the IOMUXC table for details.

4.11.10.5 IPU Display Interface Timing

The IPU Display Interface supports two kinds of display accesses: synchronous and asynchronous. There are two groups of external interface pins to provide synchronous and asynchronous controls.

4.11.10.5.1 Synchronous Controls

The synchronous control changes its value as a function of a system or of an external clock. This control has a permanent period and a permanent waveform.

There are special physical outputs to provide synchronous controls:

- The ipp_disp_clk is a dedicated base synchronous signal that is used to generate a base display (component, pixel) clock for a display.

4.11.12.6 High-Speed Clock Timing

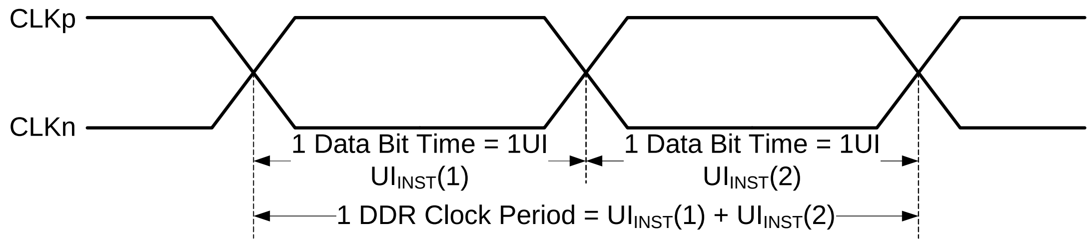


Figure 75. DDR Clock Definition

4.11.12.7 Forward High-Speed Data Transmission Timing

The timing relationship of the DDR Clock differential signal to the Data differential signal is shown in Figure 76:

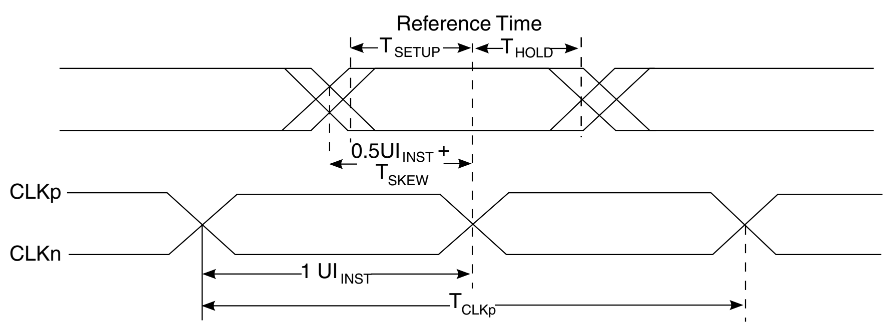


Figure 76. Data to Clock Timing Definitions

4.11.12.8 Reverse High-Speed Data Transmission Timing

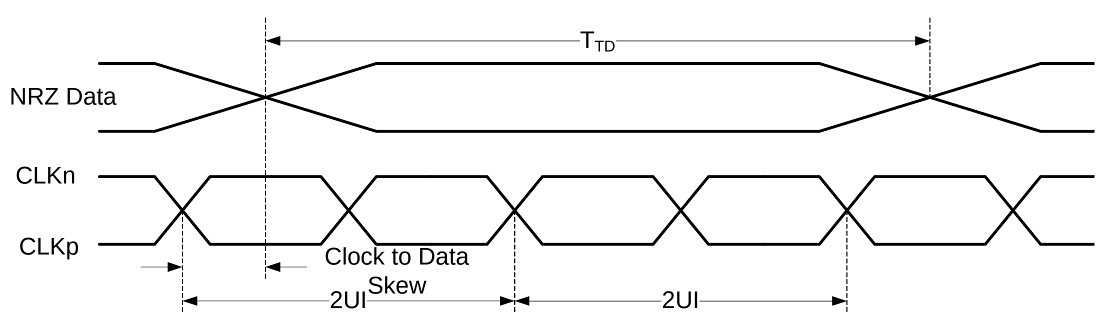


Figure 77. Reverse High-Speed Data Transmission Timing at Slave Side

Table 87. SSI Receiver Timing with Internal Clock (continued)

ID	Parameter	Min	Max	Unit
Oversampling Clock Operation				
SS47	Oversampling clock period	15.04	—	ns
SS48	Oversampling clock high period	6.0	—	ns
SS49	Oversampling clock rise time	—	3.0	ns
SS50	Oversampling clock low period	6.0	—	ns
SS51	Oversampling clock fall time	—	3.0	ns

NOTE

- All the timings for the SSI are given for a non-inverted serial clock polarity (TSCKP/RSCKP = 0) and a non-inverted frame sync (TFSI/RFSI = 0). If the polarity of the clock and/or the frame sync have been inverted, all the timing remains valid by inverting the clock signal AUDx_TXC/AUDx_RXC and/or the frame sync AUDx_TXFS/AUDx_RXFS shown in the tables and in the figures.
- All timings are on Audiomux Pads when SSI is being used for data transfer.
- AUDx_TXC and AUDx_RXC refer to the Transmit and Receive sections of the SSI.
- The terms, WL and BL, refer to Word Length (WL) and Bit Length (BL).
- For internal Frame Sync operation using external clock, the frame sync timing is same as that of transmit data (for example, during AC97 mode of operation).

5 Boot Mode Configuration

This section provides information on boot mode configuration pins allocation and boot devices interfaces allocation.

5.1 Boot Mode Configuration Pins

Table 97 provides boot options, functionality, fuse values, and associated pins. Several input pins are also sampled at reset and can be used to override fuse values, depending on the value of BT_FUSE_SEL fuse. The boot option pins are in effect when BT_FUSE_SEL fuse is ‘0’ (cleared, which is the case for an unblown fuse). For detailed boot mode options configured by the boot mode pins, see the i.MX 6Dual/6Quad Fuse Map document and the System Boot chapter of the i.MX 6Dual/6Quad reference manual (IMX6DQRM).

Table 97. Fuses and Associated Pins Used for Boot

Pin	Direction at Reset	eFuse Name
Boot Mode Selection		
BOOT_MODE1	Input	Boot Mode Selection
BOOT_MODE0	Input	Boot Mode Selection
Boot Options[1]		
EIM_DA0	Input	BOOT_CFG1[0]
EIM_DA1	Input	BOOT_CFG1[1]
EIM_DA2	Input	BOOT_CFG1[2]
EIM_DA3	Input	BOOT_CFG1[3]
EIM_DA4	Input	BOOT_CFG1[4]
EIM_DA5	Input	BOOT_CFG1[5]
EIM_DA6	Input	BOOT_CFG1[6]
EIM_DA7	Input	BOOT_CFG1[7]
EIM_DA8	Input	BOOT_CFG2[0]
EIM_DA9	Input	BOOT_CFG2[1]
EIM_DA10	Input	BOOT_CFG2[2]
EIM_DA11	Input	BOOT_CFG2[3]
EIM_DA12	Input	BOOT_CFG2[4]
EIM_DA13	Input	BOOT_CFG2[5]
EIM_DA14	Input	BOOT_CFG2[6]
EIM_DA15	Input	BOOT_CFG2[7]
EIM_A16	Input	BOOT_CFG3[0]
EIM_A17	Input	BOOT_CFG3[1]

6 Package Information and Contact Assignments

This section includes the contact assignment information and mechanical package drawing.

6.1 Updated Signal Naming Convention

The signal names of the i.MX6 series of products have been standardized to better align the signal names within the family and across the documentation. Some of the benefits of these changes are as follows:

- The names are unique within the scope of an SoC and within the series of products
- Searches will return all occurrences of the named signal
- The names are consistent between i.MX 6 series products implementing the same modules
- The module instance is incorporated into the signal name

This change applies only to signal names. The original ball names have been preserved to prevent the need to change schematics, BSDL models, IBIS models, etc.

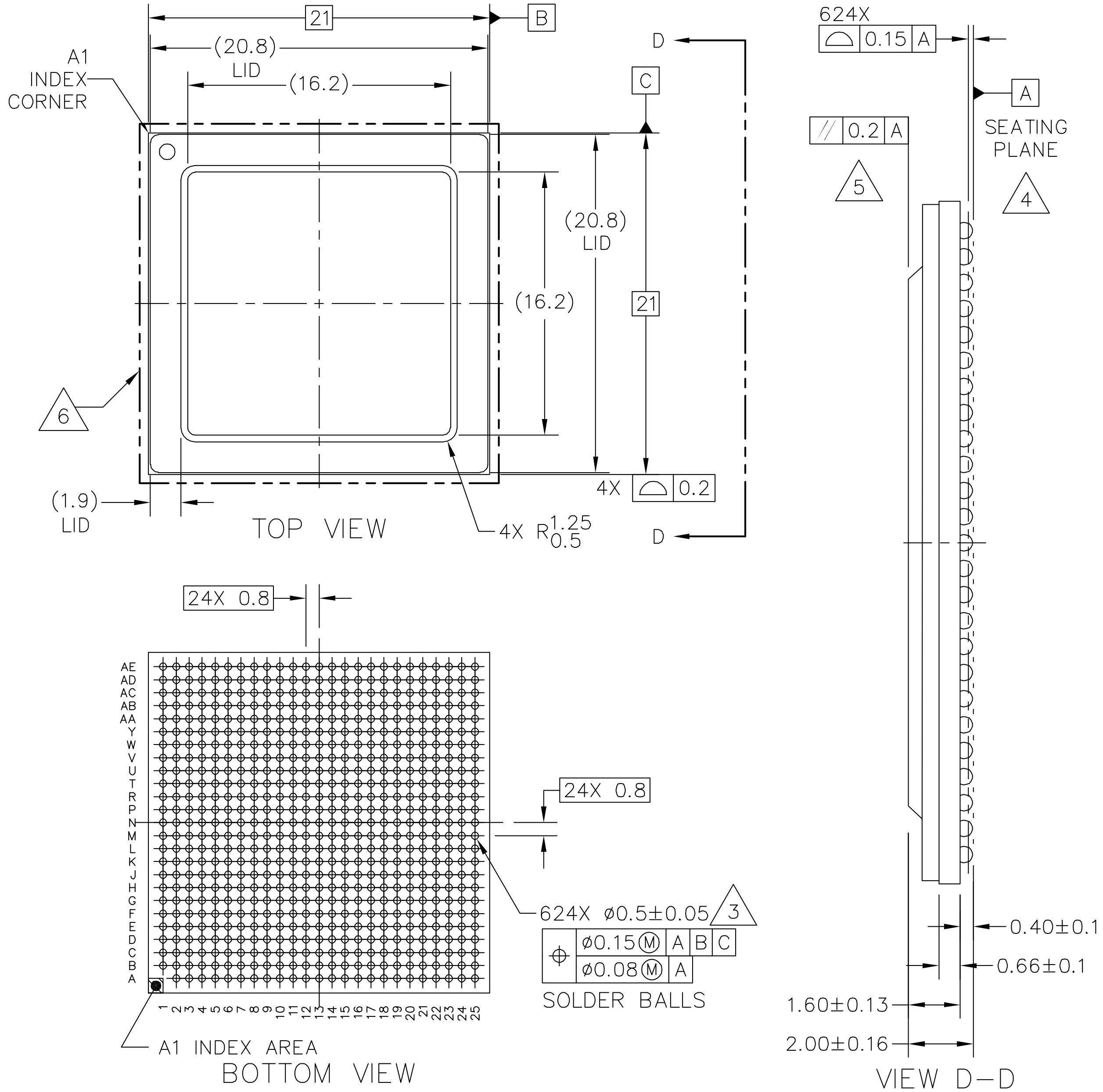
Throughout this document, the updated signal names are used except where referenced as a ball name (such as the Functional Contact Assignments table, Ball Map table, and so on). A master list of the signal name changes is in the document, *IMX 6 Series Signal Name Mapping* (EB792). This list can be used to map the signal names used in older documentation to the new standardized naming conventions.

6.2 21 x 21 mm Package Information

6.2.1 Case FCPBGA, 21 x 21 mm, 0.8 mm Pitch, 25 x 25 Ball Matrix

6.2.1.1 21 x 21 mm Lidded Package

Figure 107 shows the top, bottom, and side views of the 21 × 21 mm lidded package.



	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 624 I/O FC PBGA, 21 X 21 X 2 PKG, 0.8 MM PITCH, STAMPED LID	DOCUMENT NO: 98ASA00330D	REV: D
	STANDARD: NON–JEDEC	
		08 OCT 2013

Figure 106. 21 x 21 mm Lidded Package Top, Bottom, and Side Views (Sheet 1 of 2)

Table 100. 21 x 21 mm Functional Contact Assignments (continued)

Ball Name	Ball	Power Group	Ball Type	Out of Reset Condition[1]			
				Default Mode (Reset Mode)	Default Function (Signal Name)	Input/Output	Value[2]
DISP0_DAT18	V25	NVCC_LCD	GPIO	ALT5	GPIO5_IO12	Input	PU (100K)
DISP0_DAT19	U23	NVCC_LCD	GPIO	ALT5	GPIO5_IO13	Input	PU (100K)
DISP0_DAT2	P23	NVCC_LCD	GPIO	ALT5	GPIO4_IO23	Input	PU (100K)
DISP0_DAT20	U22	NVCC_LCD	GPIO	ALT5	GPIO5_IO14	Input	PU (100K)
DISP0_DAT21	T20	NVCC_LCD	GPIO	ALT5	GPIO5_IO15	Input	PU (100K)
DISP0_DAT22	V24	NVCC_LCD	GPIO	ALT5	GPIO5_IO16	Input	PU (100K)
DISP0_DAT23	W24	NVCC_LCD	GPIO	ALT5	GPIO5_IO17	Input	PU (100K)
DISP0_DAT3	P21	NVCC_LCD	GPIO	ALT5	GPIO4_IO24	Input	PU (100K)
DISP0_DAT4	P20	NVCC_LCD	GPIO	ALT5	GPIO4_IO25	Input	PU (100K)
DISP0_DAT5	R25	NVCC_LCD	GPIO	ALT5	GPIO4_IO26	Input	PU (100K)
DISP0_DAT6	R23	NVCC_LCD	GPIO	ALT5	GPIO4_IO27	Input	PU (100K)
DISP0_DAT7	R24	NVCC_LCD	GPIO	ALT5	GPIO4_IO28	Input	PU (100K)
DISP0_DAT8	R22	NVCC_LCD	GPIO	ALT5	GPIO4_IO29	Input	PU (100K)
DISP0_DAT9	T25	NVCC_LCD	GPIO	ALT5	GPIO4_IO30	Input	PU (100K)
DRAM_A0	AC14	NVCC_DRAM	DDR	ALT0	DRAM_ADDR00	Output	0
DRAM_A1	AB14	NVCC_DRAM	DDR	ALT0	DRAM_ADDR01	Output	0
DRAM_A10	AA15	NVCC_DRAM	DDR	ALT0	DRAM_ADDR10	Output	0
DRAM_A11	AC12	NVCC_DRAM	DDR	ALT0	DRAM_ADDR11	Output	0
DRAM_A12	AD12	NVCC_DRAM	DDR	ALT0	DRAM_ADDR12	Output	0
DRAM_A13	AC17	NVCC_DRAM	DDR	ALT0	DRAM_ADDR13	Output	0
DRAM_A14	AA12	NVCC_DRAM	DDR	ALT0	DRAM_ADDR14	Output	0
DRAM_A15	Y12	NVCC_DRAM	DDR	ALT0	DRAM_ADDR15	Output	0
DRAM_A2	AA14	NVCC_DRAM	DDR	ALT0	DRAM_ADDR02	Output	0
DRAM_A3	Y14	NVCC_DRAM	DDR	ALT0	DRAM_ADDR03	Output	0
DRAM_A4	W14	NVCC_DRAM	DDR	ALT0	DRAM_ADDR04	Output	0
DRAM_A5	AE13	NVCC_DRAM	DDR	ALT0	DRAM_ADDR05	Output	0
DRAM_A6	AC13	NVCC_DRAM	DDR	ALT0	DRAM_ADDR06	Output	0
DRAM_A7	Y13	NVCC_DRAM	DDR	ALT0	DRAM_ADDR07	Output	0
DRAM_A8	AB13	NVCC_DRAM	DDR	ALT0	DRAM_ADDR08	Output	0
DRAM_A9	AE12	NVCC_DRAM	DDR	ALT0	DRAM_ADDR09	Output	0
DRAM_CAS	AE16	NVCC_DRAM	DDR	ALT0	DRAM_CAS_B	Output	0
DRAM_CS0	Y16	NVCC_DRAM	DDR	ALT0	DRAM_CS0_B	Output	0
DRAM_CS1	AD17	NVCC_DRAM	DDR	ALT0	DRAM_CS1_B	Output	0
DRAM_D0	AD2	NVCC_DRAM	DDR	ALT0	DRAM_DATA00	Input	PU (100K)
DRAM_D1	AE2	NVCC_DRAM	DDR	ALT0	DRAM_DATA01	Input	PU (100K)
DRAM_D10	AA6	NVCC_DRAM	DDR	ALT0	DRAM_DATA10	Input	PU (100K)

Table 100. 21 x 21 mm Functional Contact Assignments (continued)

Ball Name	Ball	Power Group	Ball Type	Out of Reset Condition[1]			
				Default Mode (Reset Mode)	Default Function (Signal Name)	Input/Output	Value[2]
LVDS0_TX3_P	W1	NVCC_LVDS_2P5	LVDS	ALT0	LVDS0_TX3_P	Input	Keeper
LVDS1_CLK_N	Y3	NVCC_LVDS_2P5	LVDS	—	LVDS1_CLK_N	—	—
LVDS1_CLK_P	Y4	NVCC_LVDS_2P5	LVDS	ALT0	LVDS1_CLK_P	Input	Keeper
LVDS1_TX0_N	Y1	NVCC_LVDS_2P5	LVDS	—	LVDS1_TX0_N	—	—
LVDS1_TX0_P	Y2	NVCC_LVDS_2P5	LVDS	ALT0	LVDS1_TX0_P	Input	Keeper
LVDS1_TX1_N	AA2	NVCC_LVDS_2P5	LVDS	—	LVDS1_TX1_N	—	—
LVDS1_TX1_P	AA1	NVCC_LVDS_2P5	LVDS	ALT0	LVDS1_TX1_P	Input	Keeper
LVDS1_TX2_N	AB1	NVCC_LVDS_2P5	LVDS	—	LVDS1_TX2_N	—	—
LVDS1_TX2_P	AB2	NVCC_LVDS_2P5	LVDS	ALT0	LVDS1_TX2_P	Input	Keeper
LVDS1_TX3_N	AA3	NVCC_LVDS_2P5	LVDS	—	LVDS1_TX3_N	—	—
LVDS1_TX3_P	AA4	NVCC_LVDS_2P5	LVDS	ALT0	LVDS1_TX3_P	Input	Keeper
MLB_CN	A11	VDD_HIGH_CAP	LVDS	—	MLB_CLK_N	—	—
MLB_CP	B11	VDD_HIGH_CAP	LVDS	—	MLB_CLK_P	—	—
MLB_DN	B10	VDD_HIGH_CAP	LVDS	—	MLB_DATA_N	—	—
MLB_DP	A10	VDD_HIGH_CAP	LVDS	—	MLB_DATA_P	—	—
MLB_SN	A9	VDD_HIGH_CAP	LVDS	—	MLB_SIG_N	—	—
MLB_SP	B9	VDD_HIGH_CAP	LVDS	—	MLB_SIG_P	—	—
NANDF_ALE	A16	NVCC_NANDF	GPIO	ALT5	GPIO6_IO08	Input	PU (100K)
NANDF_CLE	C15	NVCC_NANDF	GPIO	ALT5	GPIO6_IO07	Input	PU (100K)
NANDF_CS0	F15	NVCC_NANDF	GPIO	ALT5	GPIO6_IO11	Input	PU (100K)
NANDF_CS1	C16	NVCC_NANDF	GPIO	ALT5	GPIO6_IO14	Input	PU (100K)
NANDF_CS2	A17	NVCC_NANDF	GPIO	ALT5	GPIO6_IO15	Input	PU (100K)
NANDF_CS3	D16	NVCC_NANDF	GPIO	ALT5	GPIO6_IO16	Input	PU (100K)
NANDF_D0	A18	NVCC_NANDF	GPIO	ALT5	GPIO2_IO00	Input	PU (100K)
NANDF_D1	C17	NVCC_NANDF	GPIO	ALT5	GPIO2_IO01	Input	PU (100K)
NANDF_D2	F16	NVCC_NANDF	GPIO	ALT5	GPIO2_IO02	Input	PU (100K)
NANDF_D3	D17	NVCC_NANDF	GPIO	ALT5	GPIO2_IO03	Input	PU (100K)
NANDF_D4	A19	NVCC_NANDF	GPIO	ALT5	GPIO2_IO04	Input	PU (100K)
NANDF_D5	B18	NVCC_NANDF	GPIO	ALT5	GPIO2_IO05	Input	PU (100K)
NANDF_D6	E17	NVCC_NANDF	GPIO	ALT5	GPIO2_IO06	Input	PU (100K)
NANDF_D7	C18	NVCC_NANDF	GPIO	ALT5	GPIO2_IO07	Input	PU (100K)
NANDF_RB0	B16	NVCC_NANDF	GPIO	ALT5	GPIO6_IO10	Input	PU (100K)
NANDF_WP_B	E15	NVCC_NANDF	GPIO	ALT5	GPIO6_IO09	Input	PU (100K)
ONOFF	D12	VDD_SNVS_IN	GPIO	—	SRC_ONOFF	Input	PU (100K)
PCIE_RXM	B1	PCIE_VPH	—	—	PCIE_RX_N	—	—
PCIE_RXP	B2	PCIE_VPH	—	—	PCIE_RX_P	—	—

Table 100. 21 x 21 mm Functional Contact Assignments (continued)

Ball Name	Ball	Power Group	Ball Type	Out of Reset Condition[1]			
				Default Mode (Reset Mode)	Default Function (Signal Name)	Input/Output	Value[2]
PCIE_TXM	A3	PCIE_VPH	—	—	PCIE_TX_N	—	—
PCIE_TXP	B3	PCIE_VPH	—	—	PCIE_TX_P	—	—
PMIC_ON_REQ	D11	VDD_SNVS_IN	GPIO	ALT0	SNVS_PMIC_ON_REQ	Output	Open Drain with PU (100K)
PMIC_STBY_REQ	F11	VDD_SNVS_IN	GPIO	ALT0	CCM_PMIC_STBY_REQ	Output	0
POR_B	C11	VDD_SNVS_IN	GPIO	ALT0	SRC_POR_B	Input	PU (100K)
RGMII_RD0	C24	NVCC_RGMII	DDR	ALT5	GPIO6_IO25	Input	PU (100K)
RGMII_RD1	B23	NVCC_RGMII	DDR	ALT5	GPIO6_IO27	Input	PU (100K)
RGMII_RD2	B24	NVCC_RGMII	DDR	ALT5	GPIO6_IO28	Input	PU (100K)
RGMII_RD3	D23	NVCC_RGMII	DDR	ALT5	GPIO6_IO29	Input	PU (100K)
RGMII_RX_CTL	D22	NVCC_RGMII	DDR	ALT5	GPIO6_IO24	Input	PD (100K)
RGMII_RXC	B25	NVCC_RGMII	DDR	ALT5	GPIO6_IO30	Input	PD (100K)
RGMII_TD0	C22	NVCC_RGMII	DDR	ALT5	GPIO6_IO20	Input	PU (100K)
RGMII_TD1	F20	NVCC_RGMII	DDR	ALT5	GPIO6_IO21	Input	PU (100K)
RGMII_TD2	E21	NVCC_RGMII	DDR	ALT5	GPIO6_IO22	Input	PU (100K)
RGMII_TD3	A24	NVCC_RGMII	DDR	ALT5	GPIO6_IO23	Input	PU (100K)
RGMII_TX_CTL	C23	NVCC_RGMII	DDR	ALT5	GPIO6_IO26	Input	PD (100K)
RGMII_TXC	D21	NVCC_RGMII	DDR	ALT5	GPIO6_IO19	Input	PD (100K)
RTC_XTALI	D9	VDD_SNVS_CAP	—	—	RTC_XTALI	—	—
RTC_XTALO	C9	VDD_SNVS_CAP	—	—	RTC_XTALO	—	—
SATA_RXM	A14	SATA_VPH	—	—	SATA_PHY_RX_N	—	—
SATA_RXP	B14	SATA_VPH	—	—	SATA_PHY_RX_P	—	—
SATA_TXM	B12	SATA_VPH	—	—	SATA_PHY_TX_N	—	—
SATA_TXP	A12	SATA_VPH	—	—	SATA_PHY_TX_P	—	—
SD1_CLK	D20	NVCC_SD1	GPIO	ALT5	GPIO1_IO20	Input	PU (100K)
SD1_CMD	B21	NVCC_SD1	GPIO	ALT5	GPIO1_IO18	Input	PU (100K)
SD1_DAT0	A21	NVCC_SD1	GPIO	ALT5	GPIO1_IO16	Input	PU (100K)
SD1_DAT1	C20	NVCC_SD1	GPIO	ALT5	GPIO1_IO17	Input	PU (100K)
SD1_DAT2	E19	NVCC_SD1	GPIO	ALT5	GPIO1_IO19	Input	PU (100K)
SD1_DAT3	F18	NVCC_SD1	GPIO	ALT5	GPIO1_IO21	Input	PU (100K)
SD2_CLK	C21	NVCC_SD2	GPIO	ALT5	GPIO1_IO10	Input	PU (100K)
SD2_CMD	F19	NVCC_SD2	GPIO	ALT5	GPIO1_IO11	Input	PU (100K)
SD2_DAT0	A22	NVCC_SD2	GPIO	ALT5	GPIO1_IO15	Input	PU (100K)
SD2_DAT1	E20	NVCC_SD2	GPIO	ALT5	GPIO1_IO14	Input	PU (100K)
SD2_DAT2	A23	NVCC_SD2	GPIO	ALT5	GPIO1_IO13	Input	PU (100K)
SD2_DAT3	B22	NVCC_SD2	GPIO	ALT5	GPIO1_IO12	Input	PU (100K)